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Home > Products > Socket/Card Products > Product Feature Selector > Product Details

2013310-1 Product Details _



2013310-1

Memory Sockets



Product Highlights:

- Socket Type = Memory Card
- Socket Style = SO DIMM
- Gold Flash Contact Plating, Mating Area, Material
- 204 Positions
- DRAM Type = Double Data Rate (DDR) III

View all Features



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Documentation & Additional Information

Product Drawings:

• DDR3 SODIMM SOCKET 0.6mm PITCH 204POS 9.2mm HEIGHT S... (PDF, English)

Catalog Pages/Data Sheets:

• 6-1773457-3_DDR3_DIMM_SOCKETS (PDF, Chinese (Simplified))

Product Specifications:

None Available

Application Specifications:

None Available

Instruction Sheets:

None Available

CAD Files: (CAD Format & Compression Information)

- 2D Drawing (DXF, Version C)
- 3D Model (IGES, Version C)
- 3D Model (STEP, Version C)

List all Documents

Product Features (Please use the Product Drawing for all design activity)

Product Type Features:

- Socket Style = SO DIMM
- DRAM Type = Double Data Rate (DDR) III
- PCB Mount Style = Surface Mount
- ◆ Module Orientation = Right Angle

Electrical Characteristics:

DRAM Voltage = 1.5 V

Termination Features:

• Insertion Style = Cam-In

Body Features:

- Socket Type = Memory Card
- Row-to-Row Spacing (mm [in]) = 8.20 [0.322]
- Ejector Type = Locking
- Ejector Location = Both Ends
- Latch Material = Stainless Steel
- Latch Plating = Tin
- Boss = With

Contact Features:

- Contact Plating, Mating Area, Material = Gold Flash
- ◆ Contact Base Material = Copper Alloy

- - Stack Height (mm [in]) = 9.20 [0.362]
 - Number of Rows = Dual
 - Center Key (mm [in]) = Offset Left
 - Number of Keys = 1

Industry Standards:

- RoHS/ELV Compliance = RoHS compliant, ELV compliant
- Lead Free Solder Processes = Reflow solder capable to 245°C, Reflow solder capable to 260°C
- RoHS/ELV Compliance History = Always was RoHS compliant

Identification Marking:

Keying = Standard

Operation/Application:

Application Type = DDR 3 SO-DIMM

Packaging Features:

Packaging Method = Semi-Hard Tray Assembly

Other:

- Brand = TE Connectivity
- Comment = With floating page

Housing Features: • Centerline (mm [in]) = 0.60 [0.024] ◆ Housing Material = High Temperature Thermoplastic ◆ Housing Color = Black

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